

5 *Amend*
6
7 depositing the film on the desorbed substrate from a second module, wherein the substrate is transferred from the first module to the second module through a valve without exposure of the substrate to a surrounding environment.

1 *A2* 24. (Amended) The method of claim 20 further comprising the step of maintaining the
2 supercritical carbon dioxide and a solvent in contact with the substrate to remove a
3 residue selected from the group consisting of a photoresist, a photoresist residue, and an
4 etch residue from the substrate prior to the step of depositing the metal film.

1 31. (Amended) An apparatus for depositing a metal film on a substrate comprising:
2
3 *A3* a. a transfer module;
4 b. a supercritical processing module coupled to the transfer module;
5 c. a metal deposition module;
6 d. a vacuum module coupling the metal deposition module to the transfer module;
7 and
8 e. means for transferring the substrate between the supercritical processing module and the metal deposition module.

1 41. (Amended) An apparatus for depositing a metal film on a substrate comprising:
2
3 *A4* a. a transfer module comprising an entrance and a first robot;
4 b. a supercritical processing module coupled to the transfer module;
5 c. a metal deposition module; and
6 d. a vacuum module coupling the metal deposition module to the transfer module,
7 the vacuum module comprising a vacuum chamber and a second robot, wherein
8 the first robot and the second robot are configured to transfer the substrate between the supercritical processing module and the metal deposition module.

1 42. (New) An apparatus comprising:
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3 *A5* a. a front transfer module comprising one or more supercritical modules configured
4 to treat a substrate with a supercritical solution;
5 b. a back transfer module coupled to the front transfer module, the back transfer
6 module comprising one or more deposition modules configured to deposit a layer
7 of material onto the treated substrate; and
c. means for transferring the substrate between the front transfer module and the

8 back transfer module without exposing the substrate to the environment.

1 43. (New) The apparatus of claim 42, wherein the means for transferring the substrate
2 between the first transfer module and the second transfer module comprises one or more
3 transfer robots.

1 44. (New) The apparatus of claim 42, further comprising a valve for isolating the substrate
2 within the one of the front transfer module and the back transfer module.

1 45. (New) The apparatus of claim 42, further comprising a loader module for introducing the
2 substrate.

1 46. (New) The apparatus of claim 45, wherein the loader module is coupled to the front
2 transfer module.
